

Part Number: **1N6263W-(p)-F (Date Code 0832+)**
Weight (mg): 10.48984

p = package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	0.39	0.0414	1000000	3947
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.56	2.9954	576500	164621
		Ni	7440-02-0	41.00%			410000	117077
		Mn	7439-96-5	0.60%			6000	1713
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	286
		Co	7440-48-4	0.50%			5000	1428
		Si	7440-21-3	0.15%			1500	428
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.87	0.0909	1000000	8666
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.08	0.0089	1000000	848
Encapsulation	KTMC1050G	Silicone dioxide	60676-86-0	69.00%	68.06	7.1397	690000	469635
		Ortho Creson Novolac Epoxy Resin	29690-82-2	12.25%			122500	83377
		Basic Duromer:Phenolic resin (Compound of polymeric network)	9003-35-4	5.50%			55000	37435
		Misc.	system	12.75%			127500	86780
		Carbon black	1333-86-4	0.50%			5000	3403
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.04	0.21354	1000000	20357
Total					100.00	10.48984		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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|--|---|
| Asbestos | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Hexavalent chromium compounds | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Lead and lead compounds | Radioactive Substances |
| Mercury and mercury compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Organic tin compounds | Tributyl Tin Oxide (TBTO) |